

O 15  
JAN 13 2005



PATENT

Application No.: 10/635,123

Filing Date: August 6, 2003

Applicant: Richard H. Blunk et al.

Group Art Unit: 1746

Examiner: Crepeau

Title: ADHESIVE BONDS FOR METALLIC BIPOLAR PLATES

Attorney Docket: 8540G-000179 (GM Ref. No. GP-303390)

Mail Stop DD  
Director of the U.S. Patent and Trademark Office  
P. O. Box 1450  
Alexandria, VA 22313-1450

**SECOND SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT**

Sir:

Pursuant to 37 C.F.R. §§ 1.56, 1.97 and 1.98, Applicant hereby submits an Information Disclosure Statement for consideration by the Examiner.

I. **LIST OF PATENTS, PUBLICATIONS, AND OTHER INFORMATION**

The patents, publications and other information submitted for consideration by the Office (except unpublished U.S. patent applications) are listed on Form 1449 attached hereto.

We are sending another copy of EP1009051 dated 6-14-2000 even though it was previously submitted since the prior submission of that patent had the incorrect information on Form 1449.

II. **COPIES**

A. \_\_\_\_ Submitted herewith is a legible copy of (i) each U.S. patent application publication and U.S. and foreign patent; (ii) each publication or that portion which caused it to be listed; (iii) for each cited pending U.S. application, the application specification including the claims, and any drawing of the application which caused it to be listed including the claims directed to that portion; and (iv) all other information or that portion which caused it to be listed.